ABSTRACT

A template padding method for padding edges of at least one hole on a semiconductor mask. The exposure and padding process is modulized. A padding database is developed based on the feature size and the pattern to be exposed. In the method of the present invention, the environment to be exposed is found firstly, and specific exposure module is then searched out. The padding result of the module is pre-found and stored in a database by diffraction operation, such as OPC method. Padding of a hole on a mask about a cell of a wafer can be performed directly by using a value stored. The complicated calculation can be greatly reduced. The method is adjustable according to the feature size of the product and the exposing pattern. The method can be used to random-distribution of holes on a mask surface, so as to determine a padding area effectively.